

2SA1127

Silicon PNP epitaxial planar type

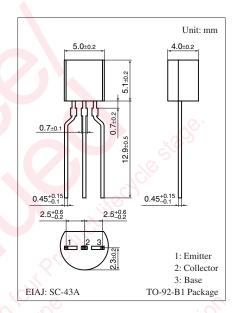
For low-frequency and low-noise amplification Complementary to 2SC2634

■ Features

- Low noise voltage NV
- High forward current transfer ratio h_{FE}

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Symbol Rating	
Collector-base voltage (Emitter open)	V_{CBO}	-60	V
Collector-emitter voltage (Base open)	V_{CEO}	-55	V
Emitter-base voltage (Collector open)	V_{EBO}	-7	V
Collector current	I_{C}	-100	mA
Peak collector current	I_{CP}	-200	mA
Collector power dissipation	P _C	400	mW
Junction temperature	T_{j}	150	°C
Storage temperature	T _{stg}	-55 to +150	°CO



■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = -10 \mu\text{A}, I_E = 0$	-60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_{\rm C} = -1 \text{mA}, I_{\rm B} = 0$	-55	, O		V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu\text{A}, I_C = 0$	-7			V
Base-emitter voltage	V _{BE}	$V_{CE} = -1 \text{ V}, I_{C} = -30 \text{ mA}$			-1	V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -10 \text{ V}, I_E = 0$		-1	-100	nA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -10 \text{ V}, I_{B} = 0$		- 0.01	-1.00	μΑ
Forward current transfer ratio *	$h_{\rm FE}$	$V_{CE} = -5 \text{ V}, I_C = -2 \text{ mA}$ 1			700	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$			- 0.6	V
Transition frequency	f_T	$V_{CB} = -5 \text{ V}, I_E = 2 \text{ mA}, f = 200 \text{ MHz}$ 200		200		MHz
Noise voltage	NV	$V_{CE} = -10 \text{ V}, I_{C} = -1 \text{ mA}, G_{V} = 80 \text{ dB}$			150	mV
		$R_g = 100 \text{ k}\Omega$, Function = FLAT				

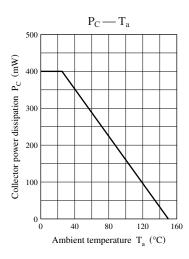
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

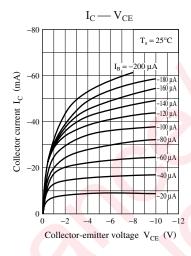
2. *: Rank classification

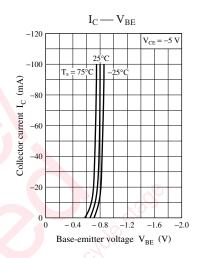
Rank	R	S	Т
h_{FE}	180 to 360	260 to 520	360 to 700

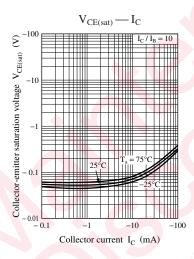
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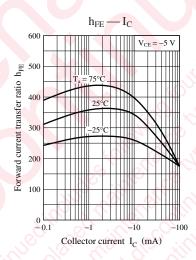
Panasonic

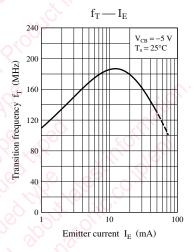


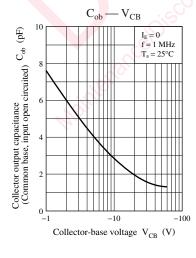


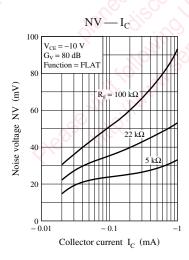












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